

MOTOROLA
SEMICONDUCTOR
TECHNICAL DATA

T46-23-12

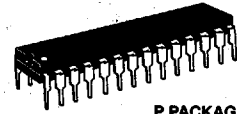
MCM6265

8K x 9 Bit Fast Static RAM

The MCM6265 is fabricated using Motorola's high-performance silicon-gate CMOS technology. Static design eliminates the need for external clocks or timing strobes, while CMOS circuitry reduces power consumption and provides for greater reliability.

This device meets JEDEC standards for functionality and pinout, and is available in plastic dual-in-line and plastic small-outline J-leaded packages.

- Single 5 V ±10% Power Supply
- Fully Static — No Clock or Timing Strokes Necessary
- Fast Access Times: 15, 20, 25 and 35 ns
- Equal Address and Chip Enable Access Times
- Output Enable (\bar{G}) Feature for Increased System Flexibility and to Eliminate Bus Contention Problems
- Low Power Operation: 110–140 mA Maximum ac
- Fully TTL-Compatible — Three-State Output



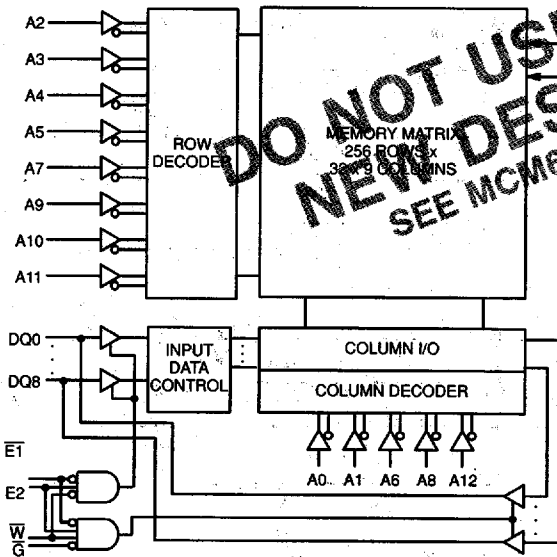
P PACKAGE
300-MIL PLASTIC
CASE 710B-01



NJ PACKAGE
300-MIL SOJ
CASE 810B-03

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BLOCK DIAGRAM



DO NOT USE FOR NEW DESIGN.
SEE MCM6265C

PIN ASSIGNMENT

A8	1	28	VCC
A7	2	27	W
A6	3	26	E2
A5	4	25	A9
A4	5	24	A10
A3	6	23	A11
A2	7	22	\bar{G}
A1	8	21	A12
A0	9	20	ET
DQ0	10	19	DQ8
DQ1	11	18	DQ7
DQ2	12	17	DQ6
DQ3	13	16	DQ5
VSS	14	15	DQ4

PIN NAMES

A0–A12	Address Input
DQ0–DQ8	Data Input/Data Output
W	Write Enable
G	Output Enable
ET, E2	Chip Enable
VCC	Power Supply (+ 5 V)
VSS	Ground

TRUTH TABLE (X = don't care)

E1	E2	G	W	Mode	VCC Current	Output	Cycle
H	X	X	X	Not Selected	ISB1, ISB2	High-Z	-
X	L	X	X	Not Selected	ISB1, ISB2	High-Z	-
L	H	H	H	Output Disabled	ICCA	High-Z	-
L	H	L	H	Read	ICCA	Dout	Read Cycle
L	H	X	L	Write	ICCA	High-Z	Write Cycle

This device contains circuitry to protect the inputs against damage due to high static voltages or electric fields; however, it is advised that normal precautions be taken to avoid application of any voltage higher than maximum rated voltages to this high-impedance circuit.

ABSOLUTE MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Power Supply Voltage	VCC	-0.5 to +7.0 V	V
Voltage Relative to VSS For Any Pin Except VCC	Vin, Vout	-0.5 to VCC + 0.5	V
Output Current	Iout	± 20	mA
Power Dissipation	PD	1.0	W
Temperature Under Bias	Tbias	-10 to +85	°C
Operating Temperature	TA	0 to +70	°C
Storage Temperature — Plastic	Tstg	-55 to +125	°C

NOTE: Permanent device damage may occur if ABSOLUTE MAXIMUM RATINGS are exceeded. Functional operation should be restricted to RECOMMENDED OPERATING CONDITIONS. Exposure to higher than recommended voltages for extended periods of time could affect device reliability.

DC OPERATING CONDITIONS AND CHARACTERISTICS

(VCC = 5.0 V ± 10%, TA = 0 to 70°C, Unless Otherwise Noted)

RECOMMENDED OPERATING CONDITIONS

Parameter	Symbol	Min	Typ	Max	Unit
Supply Voltage (Operating Voltage Range)	VCC	4.5	5.0	5.5	V
Input High Voltage	VIH	2.2	—	VCC + 0.3*	V
Input Low Voltage	VIL	-0.5**	—	0.8	V

*VIH (max) = VCC + 0.3 V dc; VIH (max) = VCC + 2.0 V ac (pulse width ≤ 20 ns)

**VIL (min) = -0.5 V dc; VIL (min) = -2.0 V ac (pulse width ≤ 20 ns)

DC CHARACTERISTICS

Parameter	Symbol	Min	Max	Unit
Input Leakage Current (All Inputs, Vin = 0 to VCC)	Ikg(I)	—	± 1	µA
Output Leakage Current (E = VIH or G = VIH, Vout = 0 to VCC)	Ikg(O)	—	± 1	µA
Output Low Voltage (IOL = 8.0 mA)	VOL	—	0.4	V
Output High Voltage (IOH = -4.0 mA)	VOH	2.4	—	V

POWER SUPPLY CURRENTS

Parameter	Symbol	-15	-20	-25	-35	Unit
AC Active Supply Current (Iout = 0 mA, VCC = Max, f = fmax)	ICCA	140	130	100	110	mA
AC Standby Current (E1 = VIH or E2 = VIL, VCC = Max, f = fmax)	ISB1	40	35	30	30	mA
Standby Current (E1 ≥ VCC - 0.2 V or E2 ≤ VSS + 0.2 V, Vin ≤ VSS + 0.2 V, or ≥ VCC - 0.2 V)	ISB2	20	20	20	20	mA

This CMOS memory circuit has been designed to meet the dc and ac specifications shown in the tables, after thermal equilibrium has been established. The circuit is in a test socket or mounted on a printed circuit board and transverse air flow of at least 500 linear feet per minute is maintained.

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CAPACITANCE (f = 1 MHz, dV = 3 V, T_A = 25°C, Periodically sampled rather than 100% tested)

Characteristic	Symbol	Max	Unit
Address and Data Input Capacitance	C _{in}	6	pF
Control Pin Input Capacitance (E ₁ , E ₂ , \bar{G} , W)	C _{in}	6	pF
Output Capacitance	C _{out}	7	pF

AC OPERATING CONDITIONS AND CHARACTERISTICS
(V_{CC} = 5 V ± 10%, T_A = 0 to + 70°C, Unless Otherwise Noted)

Input Timing Measurement Reference Level 1.5 V
Input Pulse Levels 0 to 3 V
Input Rise/Fall Time 5 ns

Output Timing Measurement Reference Level 1.5 V
Output Load Figure 1A Unless Otherwise Noted

READ CYCLE (See Notes 1 and 2)

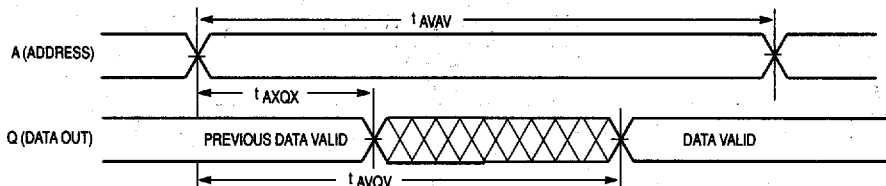
Parameter	Symbol		- 12		- 15		- 25		- 35		Unit	Notes
	Std	Alt	Min	Max	Min	Max	Min	Max	Min	Max		
Read Cycle Time	t _{AVAV}	t _{RC}	15	—	20	—	25	—	35	—	ns	3
Address Access Time	t _{AVQV}	t _{AA}	—	15	—	20	—	25	—	35	ns	
Enable Access Time	t _{ELQV}	t _{ACS}	—	15	—	20	—	25	—	35	ns	4
Output Enable Access Time	t _{GLQV}	t _{OE}	—	8	—	10	—	12	—	12	ns	
Output Hold from Address Change	t _{AXQX}	t _{OH}	4	—	4	—	4	—	4	—	ns	
Enable Low to Output Active	t _{ELQX}	t _{CLZ}	4	—	4	—	4	—	4	—	ns	5,6,7
Output Enable Low to Output Active	t _{GLQX}	t _{OLZ}	0	—	0	—	0	—	0	—	ns	5,6,7
Enable High to Output High-Z	t _{EHQZ}	t _{CHZ}	0	8	0	9	0	10	0	11	ns	5,6,7
Output Enable High to Output High-Z	t _{GHQZ}	t _{OHZ}	0	7	0	8	0	10	0	10	ns	5,6,7
Power Up Time	t _{ELICCH}	t _{PU}	0	—	0	—	0	—	0	—	ns	
Power Down Time	t _{EHICCL}	t _{PD}	—	15	—	20	—	25	—	35	ns	

NOTES:

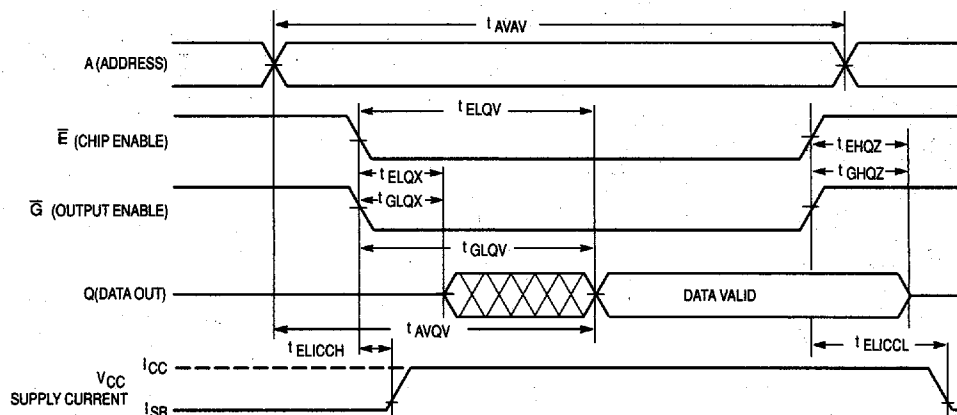
1. W is high for read cycle.
2. E₁ and E₂ are represented by \bar{E} in this data sheet. E₂ is of opposite polarity to \bar{E} .
3. All timings are referenced from the last valid address to the first transitioning address.
4. Addresses valid prior to or coincident with \bar{E} going low.
5. At any given voltage and temperature, t_{EHQZ} max < t_{ELQX} min, and t_{GHQZ} max < t_{GLQX} min, both for a given device and from device to device.
6. Transition is measured ± 500 mV from steady-state voltage with load of Figure 1B.
7. This parameter is sampled and not 100% tested.
8. Device is continuously selected ($\bar{E}1 = V_{IL}$, E₂ = V_{IH}, $\bar{G} = V_{IL}$).

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READ CYCLE 1 (See Note 8)



READ CYCLE 2 (See Note 4)



AC TEST LOADS

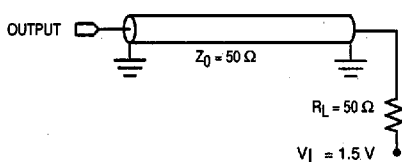


Figure 1A

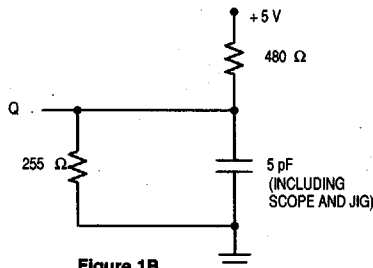
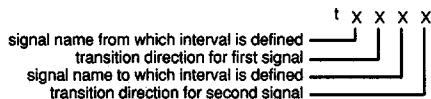


Figure 1B

TIMING PARAMETER ABBREVIATIONS



- The transition definitions used in this data sheet are:
- H = transition to high
 - L = transition to low
 - V = transition to valid
 - X = transition to invalid or don't care
 - Z = transition to off (high impedance)

TIMING LIMITS

The table of timing values shows either a minimum or a maximum limit for each parameter. Input requirements are specified from the external system point of view. Thus, address setup time is shown as a minimum since the system must supply at least that much time (even though most devices do not require it). On the other hand, responses from the memory are specified from the device point of view. Thus, the access time is shown as a maximum since the device output will be valid no later than that time.

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WRITE CYCLE (\bar{W} Controlled) (See Notes 1, 2, and 3)

Parameter	Symbol		- 15		- 20		- 25		- 35		Unit	Notes
	Std	Alt	Min	Max	Min	Max	Min	Max	Min	Max		
Write Cycle Time	t _{AVAV}	t _{WC}	15	—	20	—	25	—	35	—	ns	4
Address Setup Time	t _{AVWL}	t _{AS}	0	—	0	—	0	—	0	—	ns	
Address Valid to End of Write	t _{AVWH}	t _{AW}	12	—	15	—	17	—	20	—	ns	
Write Pulse Width	t _{WLWH} t _{WLEH}	t _{WP}	12	—	15	—	17	—	20	—	ns	
Write Pulse Width, High (Output Enable devices)	t _{WLWH} t _{WLEH}	t _{WP}	10	—	12	—	15	—	17	—	ns	5
Data Valid to End of Write	t _{DVWH}	t _{DW}	7	—	8	—	10	—	12	—	ns	
Data Hold Time	t _{WHDX}	t _{DH}	0	—	0	—	0	—	0	—	ns	
Write Low to Output High-Z	t _{WLQZ}	t _{WZ}	0	7	0	8	0	10	0	12	ns	6,7,8
Write High to Output Active	t _{WHQX}	t _{OW}	4	—	4	—	4	—	4	—	ns	6,7,8
Write Recovery Time	t _{WHAX}	t _{WR}	0	—	0	—	0	—	0	—	ns	

WRITE CYCLE (\bar{E} Controlled) (See Notes 1 and 2)

Parameter	Symbol		- 15		- 20		- 25		- 35		Unit	Notes
	Std	Alt	Min	Max	Min	Max	Min	Max	Min	Max		
Write Cycle Time	t _{AVAV}	t _{WC}	15	—	20	—	25	—	35	—	ns	4
Address Setup Time	t _{AVEL}	t _{AS}	0	—	0	—	0	—	0	—	ns	
Address Valid to End of Write	t _{AVEH}	t _{AW}	12	—	15	—	20	—	25	—	ns	
Enable to End of Write	t _{ELEH} t _{ELWH}	t _{CW}	10	—	12	—	15	—	25	—	ns	9,10
Data Valid to End of Write	t _{DVEH}	t _{DW}	7	—	8	—	10	—	15	—	ns	
Data Hold Time	t _{EHDX}	t _{DH}	0	—	0	—	0	—	0	—	ns	
Write Recovery Time	t _{EHAX}	t _{WR}	0	—	0	—	0	—	0	—	ns	

NOTES:

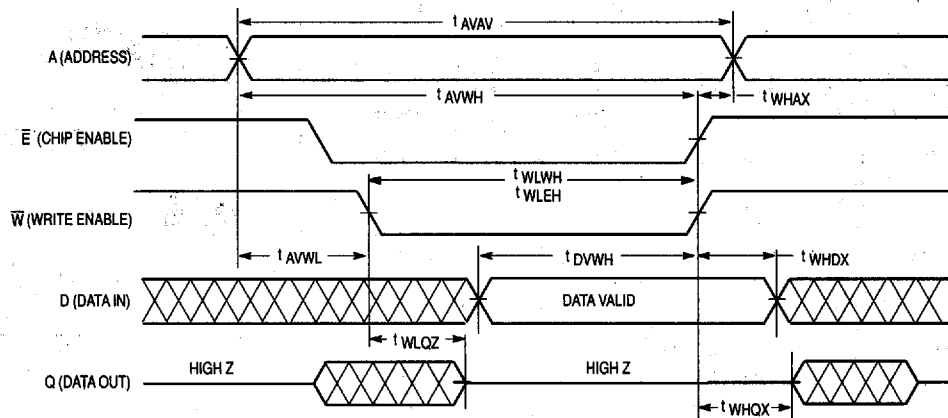
1. A write occurs during the overlap of \bar{E} low and \bar{W} low.
2. $\bar{E}1$ and $\bar{E}2$ are represented by \bar{E} in this data sheet. $\bar{E}2$ is of opposite polarity to \bar{E} .
3. If \bar{G} goes low coincident with or after \bar{W} goes low, the output will remain in a high-impedance state.
4. All timings are referenced from the last valid address to the first transitioning address.
5. If $\bar{G} \geq V_{IH}$, the output will remain in a high-impedance state.
6. At any given voltage and temperature, t_{WLQZ} max < t_{WHQX} min, both for a given device and from device to device.
7. Transition is measured ± 500 mV from steady-state voltage with load of Figure 1B.
8. This parameter is sampled and not 100% tested.
9. If \bar{E} goes low coincident with or after \bar{W} goes low, the output will remain in a high-impedance state.
10. If \bar{E} goes high coincident with or before \bar{W} goes high, the output will remain in a high-impedance state.

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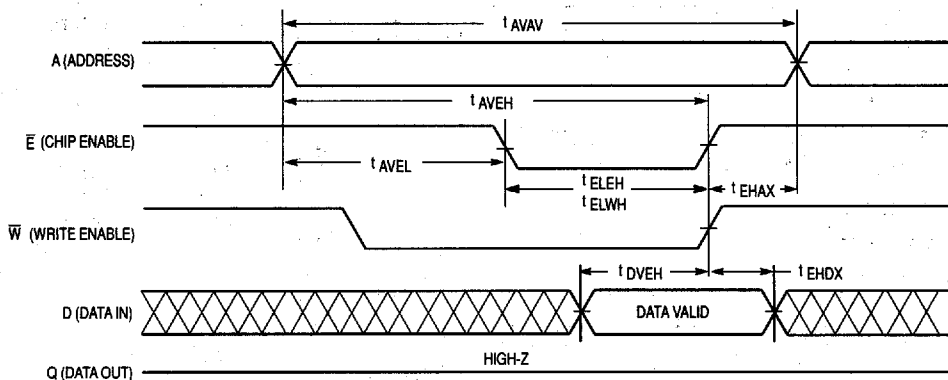
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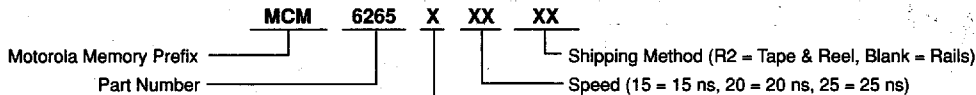
WRITE CYCLE 1 (See Notes 1, 2, and 3)



WRITE CYCLE 2 (See Notes 1 and 2)



ORDERING INFORMATION (Order by Full Part Number)



Package (P = 300-mil Plastic DIP, NJ = 300-mil SOJ)

Full Part Numbers—	MCM6265P15	MCM6265NJ15	MCM6265NJ15R2
	MCM6265P20	MCM6265NJ20	MCM6265NJ20R2
	MCM6265P25	MCM6265NJ25	MCM6265NJ25R2

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